Research Triangle Park, NC. May 13, 2015 – The International Microelectronics Assembly & Packaging Society (IMAPS) announces the release of its program for the 4th Advanced Technology Workshop and Tabletop Exhibition on Automotive Microelectronics and Packaging. The Automotive ATW will take place June 3-4, 2015 in Dearborn, MI.

This ATW is focused on key developments in automotive electronic and sensor packaging. It features presentations on advanced technologies that are pushing the envelope of packaging: especially in the areas of systems & applications, design, and materials & processes.

Dr. Steve Bezuk, Senior Director of IC Package Engineering at Qualcomm, and Bob Knoell, Quality Manager at NXP Semiconductors will keynote the event.

The two-day Automotive ATW program is sponsored by Inventec and Fastech Synergy Phillippines, Inc. Please visit [www.imaps.org/automotive](http://www.imaps.org/automotive) for the complete program and registration information.